

**MULTI-CHIP MODULE HAVING BONDING WIRES AND METHOD OF  
FABRICATING THE SAME**

**ABSTRACT OF THE DISCLOSURE**

5        Provided herein are multi-chip modules (MCMs) having bonding wires and  
fabrication methods thereof. The multi-chip module includes a substrate and a plurality of  
chips sequentially stacked. At least one top chip, stacked above a lowest chip, has an  
insulating film that covers the backside thereof. Also, each of the stacked chips has bonding  
pads formed on the periphery or edges of its upper surface. At least one insulator is  
10      interposed between the stacked chips. The insulator exposes the pads on the underlying chip.  
The pads of the respective chips are connected to a set of interconnections, which are  
disposed on the substrate. This configuration of stacked chips enables the overall height of  
the memory module to be reduced because the insulating film prevents the bonding wires  
from contacting the substrate of the top chips.

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